

**AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph beginning at page 1, line 24 that ends at page 2, line 19 with the following rewritten paragraph:

-- To produce the copper-clad laminate, the copper foil is bonded to the insulating film coated with an adhesive layer by the application of heat and pressure. Accordingly, production of the copper-clad laminate inevitably involves the handling of single copper foil. The copper foil, however, becomes limper with reduction of thickness. For the copper foil to be handled singly, the lower limit of thickness is approximately 9 to 12  $\mu\text{m}$ . The copper foil having any smaller thickness is extremely difficult to handle such that it must be fixed on a support. When a copper-clad laminate includes such an extremely thin copper foil that is bonded to an insulating film with an adhesive, fabrication of a wiring pattern produces a printed wiring board that is liable to suffer warpage due to thermal shrinkage of the adhesive that bonds the copper foil. In particular, there has been a need for printed wiring boards reduced in thickness and weight to meet the size and weight reduction of electronic equipment. It has been increasingly difficult to meet such printed wiring board needs with the above three-layer copper-clad laminate consisting of an insulating film, an adhesive and a copper foil. --

Please replace the paragraph at page 3, line 8 with the following rewritten paragraph:

-- Patent Document 1 (JP-A-2003-188495) discloses a printed wiring board fabrication process comprising etching a metal-coated polyimide film to create a pattern, in which the metal-coated polyimide film includes a first metal layer provided on the polyimide resin film by a dry metal layer production process and a second conductive metal layer plated on the first metal layer, wherein the etching is followed by a rinsing treatment of the etched surface with an oxidant. Patent Document 1 discloses Example 5 in which a nickel-chrome alloy was deposited in a thickness of 10 nm by plasma deposition, and subsequently copper was deposited in a thickness of 8  $\mu\text{m}$  by plating. --

Please DELETE the text at page 5, lines 12 and 14, in its entirety.

Please insert the following section heading at page 6, before line 5:

-- SUMMARY OF THE INVENTION --

Please replace the paragraphs beginning at page 8, line 18 and ending at line 23 with the following rewritten paragraphs:

-- ~~Fig. 1 is~~Figs. 1(a) - 1(h) are a set of sectional views of a board ~~inde~~depicting various steps of manufacturing a printed wiring board according to the present invention;

~~Fig. 2 is~~Figs. 2(a) - 2(g) are a set of sectional views of a board ~~in~~also depicting various steps of manufacturing a printed wiring board according to the present invention; --

Please replace the paragraphs beginning at page 9, line 10 and ending at line 23 with the following replacement paragraph:

-- Fig. 7 is a sectional view of a printed wiring pattern fabricated by a conventional process; ~~wherein:~~

~~11...Polyimide film~~

~~13...Base metal layer (first metal layer or seed layer)~~

~~15...Sputtered copper layer~~

~~17...Plated copper layer~~

~~20...Copper layer~~

~~21...Depth~~

~~22...Desired pattern of photosensitive resin~~

~~24...Substrate base~~

~~26...Upper end of the base metal layer~~

~~27...Surface of the insulating film~~

~~28...Lower end of the wiring pattern (conductive metal layer)--~~

Please replace the section heading at page 10, line 1 with the following rewritten section heading:

-- ~~PREFERRED EMBODIMENTS~~DETAILED DESCRIPTION OF THE INVENTION --

Please DELETE the section heading at page 36, line 1.